

In the Claims:

Claim 1 (currently amended). An integrated circuit component, comprising:

a plurality of circuit points being not externally accessible, providing various electrical signals of the integrated circuit component to be ~~measured or analyzed~~ monitored for test purposes;

at least one connecting contact point externally accessible; and

a multiplexer having an output connected to said at least one connecting contact point and having a plurality of inputs, each one of said plurality of inputs being connected to a respective one of said plurality of circuit points.

Claim 2 (currently amended). The integrated circuit component according to claim 1, wherein:

said at least one connecting contact point is one of a plurality of connecting contact points;

a reference signal is selectively applied to one of said plurality of connecting contact points and passed on via a route within the integrated circuit component to one of said plurality of circuit points that are not externally accessible; and

said electrical signals ~~to be measured or analyzed~~ can be selectively passed on via routes within the integrated circuit component from said plurality of circuit points that are not externally accessible to said plurality of connecting contact points other than said one of said plurality of connecting contact points.

Claim 3 (currently amended). The integrated circuit component according to claim 2, wherein said plurality of connecting contact points is exactly two connecting contact points.

Claim 4 (currently amended). The integrated circuit component according to claim 1, wherein:

said electrical signals are internal chip signals in the integrated circuit component; and

reference signals and said electrical signals can be selectively passed on to said at least one connecting contact point.

Claim 5 (withdrawn). The integrated circuit according to claim 1, comprising a package and wherein:

said plurality of connecting contact points define a plurality of inaccessible contact points disposed on said package;

said electrical signals at said plurality of circuit points that are not externally accessible are present at said plurality of inaccessible contact points;

said electrical signals and reference signals are selectively passed on to said at least one connecting contact point; and

said at least one connecting contact point is formed by at least one of said plurality of inaccessible contact points.

Claim 6 (withdrawn). The integrated circuit according to claim 5, wherein:

said package is a ball grid array package having a lower face;

said plurality of inaccessible contact points are located on said lower face of said package and are thus concealed between said package and a system board on which said package is fitted; and

said at least one connecting contact point is electrically conductively connected to a corresponding number of metallic test points on the system board.

Claim 7 (currently amended). The integrated circuit component according to claim 3, further comprising a second multiplexing circuit.

Claim 8 (withdrawn). The integrated circuit according to claim 1, wherein:

said multiplexing circuit is time-controlled and is provided in the integrated circuit component surrounded by a ball grid array package.

Claim 9 (currently amended). The integrated circuit component according to claim 7, wherein said multiplexing circuit is programmably controlled to predetermine selective passing on of the electrical signals to said at least one connecting contact point.

Claim 10 (currently amended). The integrated circuit component according to claim 1, wherein said at least one connecting contact point can be selectively used in an opposite operating direction for inputting signals to said plurality of circuit points that are not externally accessible.

Claim 11 (currently amended). The integrated circuit according to claim 1, wherein said at least one connecting contact point is connected to a component tester for analyzing the electrical signals ~~at, at least some of said plurality of circuit points.~~

Claim 12 (currently amended). The integrated circuit component according to claim 1, wherein said at least one connecting contact point is connected to a system analyzer and an application of said system analyzer analyzes the electrical signals ~~at~~ of, at least some of said plurality of circuit points.

Claim 13 (cancelled).

Claim 14 (withdrawn). An integrated circuit component, comprising:

a package;

a plurality of contact points for connection to an external component and disposed on said package;

a test contact point for connection to the external component and disposed on said package; and

a multiplexer having an output connected to said test contact point and having a plurality of inputs, each one of said plurality of inputs connected to a respective one of said plurality of contact points.

Claim 15 (withdrawn). The integrated circuit according to claim 14, comprising:

a first set of contact points defined by said plurality of contact points;

a second set of contact points for connection to an external component and disposed on said package;

a first test contact point defined by said test contact point;

a second test contact point for connection to the external component and disposed on said package;

a first multiplexer defined by said multiplexer, each one of said plurality of inputs connected to a respective one of said first set of said plurality of contact points; and

a second multiplexer having an output connected to said second test contact point and having a plurality of inputs, each one of said plurality of inputs of said second multiplexer connected to a respective one of said second set of contact points.

Claim 16 (withdrawn). The integrated circuit according to claim 14, wherein said package is a ball grid array package.

Claim 17 (currently amended). An integrated circuit component, comprising:

a first plurality of circuit points of the integrated circuit component not being externally accessible;

a second plurality of circuit points of the integrated circuit not being externally accessible;

a first connecting contact point being externally accessible;

a second connecting contact point being externally accessible;

a first multiplexer having an output connected to said first connecting contact point and having a plurality of inputs, each one of said plurality of inputs being connected to a respective one of said first plurality of circuit points; and

a second multiplexer having an output connected to said second connecting contact point and having a plurality of inputs, each one of said plurality of inputs being connected to a respective one of said second plurality of circuit points.

Claim 18 (currently amended). The integrated circuit component according to claim 17, wherein:

said first connecting contact point receives and passes on a reference signal via a route within the integrated circuit component to one of said first plurality of circuit points that are not externally accessible; and

said second plurality of circuit points of the integrated circuit are providing electrical signals to be ~~measured or analyzed~~ monitored for test purposes, one of said second

plurality of circuit points being connected to said second  
connecting contact point.